AUTOMOTIVE GRADE



AUIRFIZ34N

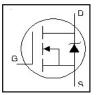
Features

- Advanced Planar Technology
- Low On-Resistance
- Isolated Package
- High Voltage Isolation = 2.5KVRMS (\$)
- Sink to Lead Creepage Distantce = 4.8mm
- 175°C Operating Temperature
- Fully Avalanche Rated
- Lead-Free, RoHS Compliant
- Automotive Qualified*

Description

Specifically designed for Automotive applications, this cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

HEXFET® Power MOSFET



V _{(BR)DSS}		55V
R _{DS(on)}	max.	40m $Ω$
I_D		21A



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	21	
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V	15	А
I _{DM}	Pulsed Drain Current ①⑥	100	
P _D @T _C = 25°C	Power Dissipation	37	W
	Linear Derating Factor	0.24	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy (Thermally Limited)@6	110	mJ
I _{AR}	Avalanche Current ①®	16	Α
E _{AR}	Repetitive Avalanche Energy ①	3.7	mJ
dv/dt	Peak Diode Recovery dv/dt 36	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ♥		4.1	°C/W
$R_{\theta JA}$	Junction-to-Ambient		65	

HEXFET® is a registered trademark of International Rectifier.

^{*}Qualification standards can be found at http://www.irf.com/

Static Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	55			٧	$V_{GS} = 0V, I_D = 250\mu A$
$\DeltaV_{(BR)DSS}/\DeltaT_{J}$	Breakdown Voltage Temp. Coefficient		0.052		V/°C	Reference to 25°C, I _D = 1mA ®
R _{DS(on)}	Static Drain-to-Source On-Resistance			40	mΩ	$V_{GS} = 10V, I_D = 11A $ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
gfs	Forward Transconductance	6.5			S	V _{DS} = 25V, I _D = 16A ⑥
I _{DSS}	Drain-to-Source Leakage Current			25	μΑ	$V_{DS} = 55V, V_{GS} = 0V$
				250		$V_{DS} = 44V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			100	nA	V _{GS} = 20V
ì	Gate-to-Source Reverse Leakage			-100		V _{GS} = -20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
Qg	Total Gate Charge			34	010	I _D = 16A
Q _{gs}	Gate-to-Source Charge			68	nC	$V_{DS} = 44V$
Q_{gd}	Gate-to-Drain ("Miller") Charge			14		V _{GS} = 10V, See Fig. 6&13 ⊕ ®
t _{d(on)}	Turn-On Delay Time		7.0			$V_{DD} = 28V$
t _r	Rise Time		49			I _D = 16A
t _{d(off)}	Turn-Off Delay Time		31		ns	$R_G = 18\Omega$
t _f	Fall Time		40			$R_D = 1.8\Omega$, See Fig. 10 \oplus \oplus
L _D	Internal Drain Inductance		4.5			Between lead,
					nH	6mm (0.25in.)
Ls	Internal Source Inductance		7.5			from package
						and center of die contact
Ciss	Input Capacitance		700			$V_{GS} = 0V$
Coss	Output Capacitance		240		рF	$V_{DS} = 25V$
C _{rss}	Reverse Transfer Capacitance		100			f = 1.0MHz, See Fig. 5 ©
С	Drain to Sink Capacitance		12			f = 1.0 MHz

Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
IS	Continuous Source Current			21		MOSFET symbol
	(Body Diode)				Α	showing the
I _{SM}	Pulsed Source Current			100		integral reverse
	(Body Diode) ①					p-n junction diode.
V_{SD}	Diode Forward Voltage			1.6	V	$T_J = 25^{\circ}C$, $I_S = 11A$, $V_{GS} = 0V$ @
t _{rr}	Reverse Recovery Time		57	86	ns	T _J = 25°C, I _F = 16A
Q _{rr}	Reverse Recovery Charge		130	200	nC	di/dt = 100A/µs
t _{on}	Forward Turn-On Time	Intrinsic	turn-on t	imeis ne	gigbe(t	turn-onis cominated by LS+LD)

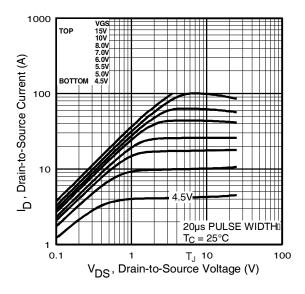
- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② $V_{DD} = 25V$, starting $T_J = 25$ °C, $L = 610\mu H$ $R_G = 25\Omega$, $I_{AS} = 16A$. (See Figure 12) ③ $I_{SD} \le 16A$, $di/dt \le 420A/\mu s$, $V_{DD} \le V_{(BR)DSS}$,
- $T_J \le 175$ °C.
- 4 Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.
- ⑤ t=60s, f=60Hz
- © Uses IRFZ34N data and test conditions.
- $\ensuremath{\mathfrak{D}}$ R_θ is measured at Tj at approximately 90°C.

Qualification Information[†]

		Automotive			
		(per AEC-Q101)			
Qualificati	on Level	Comments: This part number(s) passed Automotive qualific IR's Industrial and Consumer qualification level is grante extension of the higher Automotive level.			
Moisture S	Sensitivity Level	TO-220 Fullpak N/A			
	Machine Model	Class M2 (+/- 200V) ^{††}			
		AEC-Q101-002			
FOR	Human Body Model		Class H1A (+/- 500V) ^{††}		
ESD		AEC-Q101-001			
	Charged Device Model	Class C5 (+/- 2000V) ^{††}			
		AEC-Q101-005			
RoHS Com	npliant	Yes			

[†] Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

^{††} Exceptions to AEC-Q101 requirements are noted in the qualification report.



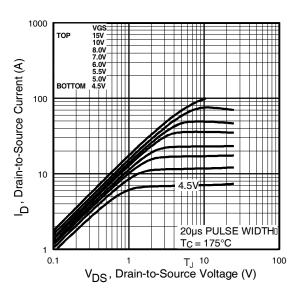
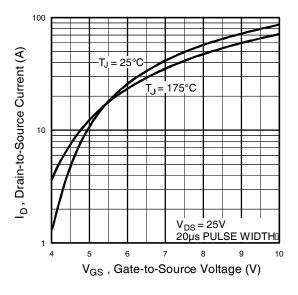


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics



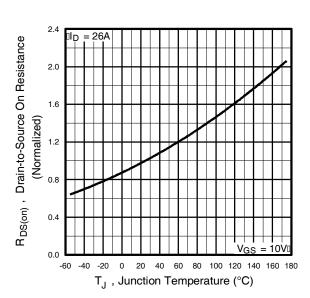
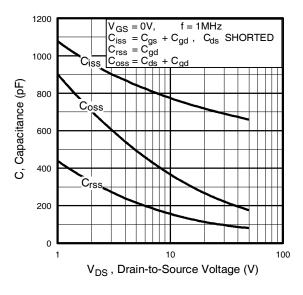


Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance Vs. Temperature



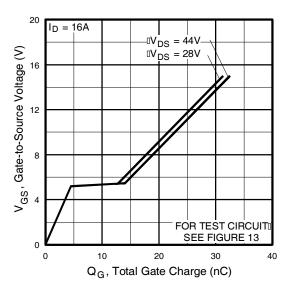
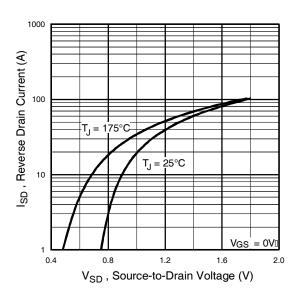


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage



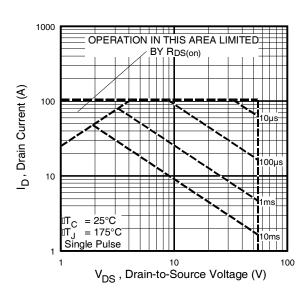
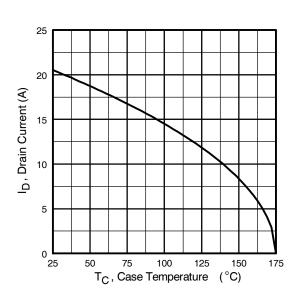


Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area

e.

stics



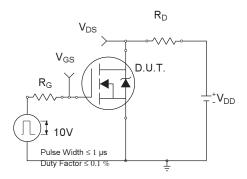


Fig 10a. Switching Time Test Circuit

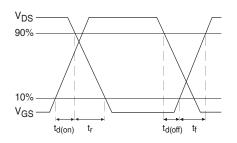


Fig 9. Maximum Drain Current Vs.
Case Temperature

Fig 10b. Switching Time Waveforms

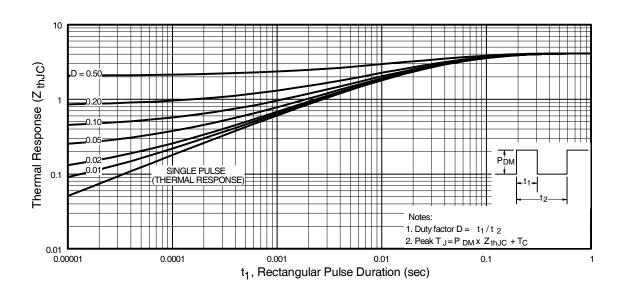


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

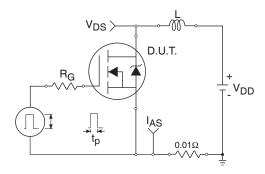


Fig 12a. Unclamped Inductive Test Circuit

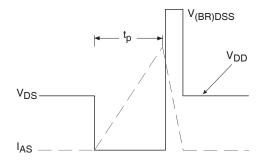


Fig 12b. Unclamped Inductive Waveforms

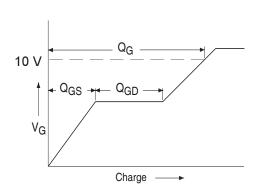


Fig 13a. Basic Gate Charge Waveform

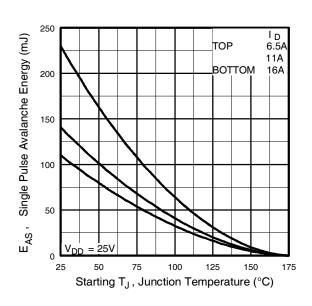


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

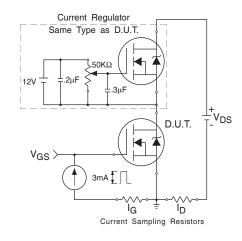
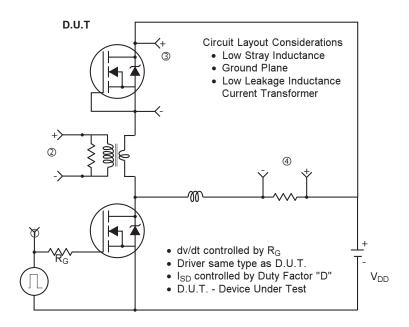
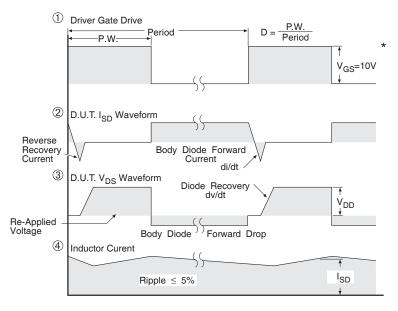


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



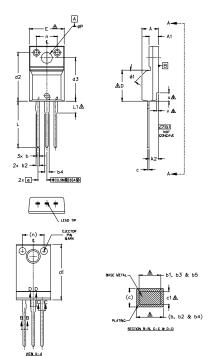


* V_{GS} = 5V for Logic Level Devices

Fig 14. For N-Channel HEXFETS

TO-220AB Full-Pak Package Outline

Dimensions are shown in millimeters (inches)



	_				
S Y M		DIMEN	ISIONS		Ņ
B	MILLIM	ETERS	TERS INCHES		Q T
L	MIN.	MAX,	MIN.	MAX.	É S
Α	4.57	4.83	.180	.190	
A1	2,57	2.83	.101	.111	
A2	2,51	2,93	.099	.115	
b	0.61	0.94	.024	.037	
b1	0.61	0.89	.024	.035	5
b2	0.76	1.27	.030	.050	
b3	0.76	1.22	.030	.048	5
b4	1.02	1.52	.040	.060	
b5	1.02	1.47	.040	.058	5
С	0,33	0.63	.013	.025	
c1	0.33	0.58	.013	.023	5
D	8.66	9.80	.341	.386	4
d1	15.80	16,13	.622	.635	
d2	13,97	14.22	.550	.560	
d3	12.30	12.93	.484	.509	
E	9.63	10.75	.379	.423	4
е	2.54	BSC	,100	BSC	1
L	13,20	13,72	.520	.540	1
L1	3.37	3.67	.122	.145	3
n	6.05	6.60	.238	.260	
ØΡ	3.05	3,45	.120	.136	
u	2.40	2,50	.094	.098	6
v	0.40	0.50	.016	.020	6
ø1	-	45*	-	45*	
	•				

NOTES:

1.0 DIMENSIONING AND TOLERANCING AS PER ASME 114.5 M- 1994.

2.0 DIMENSIONIS ARE SHOWN IN MILLIMETERS [NICHES]

ALL DIMENSION DE ED NOT INCLUDE WOOD FLASH. WILD FLASH SHALL NOT EXCEED

1.005 (10.17) PER SIDE. TIESES DIMENSIONIS ARE MEASURED AT THE OUTER WOST

EXTREMES OF THE PLASTIC BOOY.

ADMINISTRATION 15, 35 & & c. of APPLY TO BASE METAL OUT.

ALL SIEP OPTIONAL ON PLASTIC BOOY DEFINED BY DIMENSIONS u. & v.

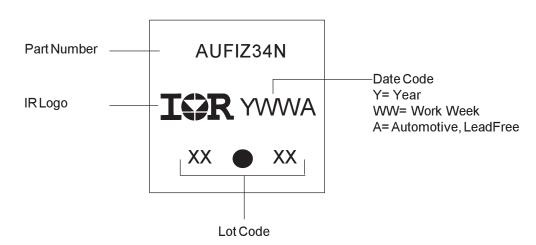
7.0 CONTROLLING DIMENSION: NICHES.

LEAD ASSIGNMENTS

HEXFET 1.- GATE 2.- DRAIN 3.- SOURCE

IGBTs, CoPACK 1,- GATE 2.- COLLECTOR 3.- EMITTER

TO-220AB Full-Pak Part Marking Information



Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFIZ34N	TO-220 Fullpak	Tube	50	AUIRFIZ34N

AUIRFIZ34N

IMPORTANT NOTICE

Unless specifically designated for the automotive market, International Rectifier Corporation and its subsidiaries (IR) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or services without notice. Part numbers designated with the "AU" prefix follow automotive industry and/or customer specific requirements with regards to product discontinuance and process change notification. All products are sold subject to IR's terms and conditions of sale supplied at the time of order acknowledgment.

IR warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with IR's standard warranty. Testing and other quality control techniques are used to the extent IR deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

IR assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using IR components. To minimize the risks with customer products and applications, customers should provide adequate design and operating safeguards.

Reproduction of IR information in IR data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alterations is an unfair and deceptive business practice. IR is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of IR products or serviced with statements different from or beyond the parameters stated by IR for that product or service voids all express and any implied warranties for the associated IR product or service and is an unfair and deceptive business practice. IR is not responsible or liable for any such statements.

IR products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or in other applications intended to support or sustain life, or in any other application in which the failure of the IR product could create a situation where personal injury or death may occur. Should Buyer purchase or use IR products for any such unintended or unauthorized application, Buyer shall indemnify and hold International Rectifier and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that IR was negligent regarding the design or manufacture of the product.

IR products are neither designed nor intended for use in military/aerospace applications or environments unless the IR products are specifically designated by IR as military-grade or "enhanced plastic." Only products designated by IR as military-grade meet military specifications. Buyers acknowledge and agree that any such use of IR products which IR has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

IR products are neither designed nor intended for use in automotive applications or environments unless the specific IR products are designated by IR as compliant with ISO/TS 16949 requirements and bear a part number including the designation "AU". Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, IR will not be responsible for any failure to meet such requirements.

For technical support, please contact IR's Technical Assistance Center

http://www.irf.com/technical-info/

WORLD HEADQUARTERS:

101 N. Sepulveda Blvd., El Segundo, California 90245 Tel: (310) 252-7105

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Infineon manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E GROUP A 5962-8877003PA NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE222 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE6400A NTE2910 NTE2916 NTE2956 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P54TU,LF SSM6P69NU,LF DMP22D4UFO-7B